



Material Content Data Sheet



Sales Product Name		TLE7718G		Issued		25. September 2017			
MA#		MA001026360							
Package		PG-DSO-52-6		Weight*		871.89 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	27.549	3.16	3.16	31597	31597	
leadframe	inorganic material	phosphorus	7723-14-0	0.073	0.01		84		
	non noble metal	zinc	7440-66-6	0.293	0.03		336		
	non noble metal	iron	7439-89-6	5.854	0.67		6714		
wire	non noble metal	copper	7440-50-8	237.701	27.26	27.97	272629	279763	
	noble metal	gold	7440-57-5	3.083	0.35	0.35	3536	3536	
	encapsulation	organic material	carbon black	1333-86-4	1.163	0.13		1334	
encapsulation	plastics	epoxy resin	-	53.484	6.13		61343		
	inorganic material	silicondioxide	60676-86-0	526.706	60.42	66.68	604099	666776	
leadfinish	non noble metal	tin	7440-31-5	7.508	0.86	0.86	8611	8611	
plating	noble metal	silver	7440-22-4	0.935	0.11	0.11	1072	1072	
glue	plastics	epoxy resin	-	1.885	0.22		2161		
	noble metal	silver	7440-22-4	5.654	0.65	0.87	6484	8645	
*deviation	< 10%				Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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